

## ABSTRACT

An adhesive composition, containing an epoxy resin (A), an epoxy resin curing agent (B), a polymer component (C) and an inorganic filler (D), in which

5 the inorganic filler (D) satisfies the condition (1) of (an average particle diameter (d50) is 0.1 to 3.5  $\mu\text{m}$ ) and condition (2) of (a ratio of a particle diameter at 90% cumulative distribution frequency (d90) to the average particle diameter (d50) is 5.0 or less), and a proportion of the inorganic filler (D) in a total content of the epoxy resin (A), the epoxy resin curing agent (B), the polymer component (C) and

10 the inorganic filler (D) is 20 to 70% by volume;

a film-like adhesive and a production method thereof; and

a semiconductor package and a production method thereof.

(No Suitable Fig.)